

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hyung Chul LEE</td> <td>07/01/2010</td> </tr> <tr> <td>Chang Hun KIM</td> <td>07/01/2010</td> </tr> <tr> <td>Jin Woo SHIN</td> <td>07/01/2010</td> </tr> <tr> <td>Hyeon Ji JEON</td> <td>07/01/2010</td> </tr> <tr> <td>Seung Min JEUNG</td> <td>07/01/2010</td> </tr> </tbody> </table>		Name	Execution Date	Hyung Chul LEE	07/01/2010	Chang Hun KIM	07/01/2010	Jin Woo SHIN	07/01/2010	Hyeon Ji JEON	07/01/2010	Seung Min JEUNG	07/01/2010
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CORRESPONDENCE DATA													
<p>Fax Number: (703)288-5139</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 703-288-5105</p> <p>Email: patent@park-law.com</p> <p>Correspondent Name: H.C. Park & Associates, PLC</p> <p>Address Line 1: 8500 Leesburg Pike</p> <p>Address Line 2: Suite 7500</p> <p>Address Line 4: Vienna, VIRGINIA 22182</p>													
ATTORNEY DOCKET NUMBER:	P3917US00												

OP \$40.00 12860560

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PATENT
REEL: 025189 FRAME: 0416

NAME OF SUBMITTER:

Hae-Chan Park

Total Attachments: 3

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ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

☒ an application for United States Letters Patent entitled **COMMUNICATION TERMINAL AND METHOD FOR DATA TRANSMISSION** ("Application");

☐ upon which United States Letters Patent, Patent Number _____, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

PANTECH CO., LTD.
PANTECH Bldg., I-2, DMC, Sangam-dong
Mapo-gu
Seoul 121-792
Republic of Korea

PANTECH CO., LTD. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.



IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: Hyung Chul LEE

Address: #302, 357-26, Hapjeong-dong, Mapo-gu
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First Inventor's Signature:

Date:

7/01/10

Second Inventor's Name: Chang Hun KIM

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Republic of Korea

Second Inventor's Signature:

Date:

7/01/10

Third Inventor's Name: Jin Woo SHIN

Address: #3-3, 109-59, Nogosan-dong, Mapo-gu
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Republic of Korea

Third Inventors' Signature:

Date:

7/01/10

Fourth Inventor's Name: Hyeon Ji JEON

Address: #109-1404, Hongjewon Hyundai Apt.,
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Seoul 120-788
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Fourth Inventor's Signature:



Date:

9/01/10

Fifth Inventor's Name

Seung Min JEUNG

Address:

#108, 120-15, Sangdo-dong, Dongjak-gu
Seoul 156-030
Republic of Korea

Fifth Inventor's Signature:

Date:

9/01/10